VARISCITE LTD
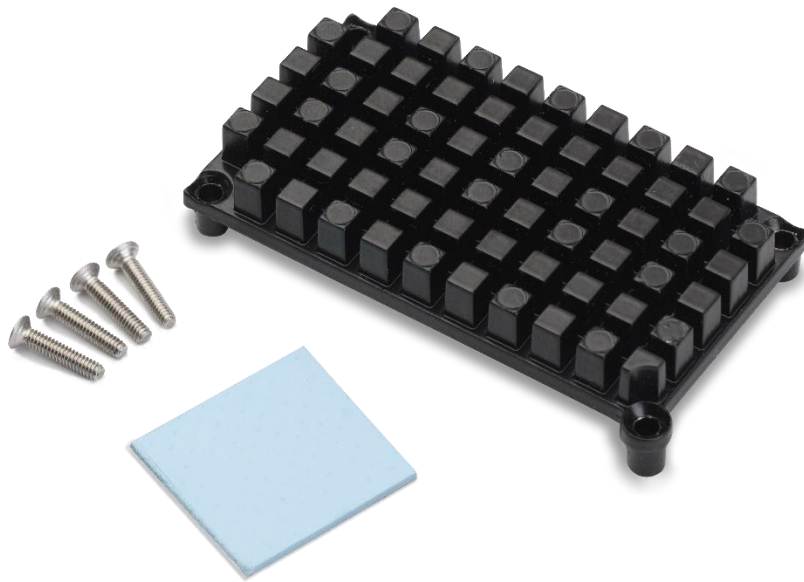
VHP-DT8MM/P Heat Sink Kit For:
DART-MX8M, DART-MX8M-MINI, DART-MX8M-PLUS

VARISCITE LTD.

VHP-DT8MM/P Heat Sink

1. Revision History

Revision	Date	Notes
1.00	Jun 13 2021	Initial – Preliminary

2. Table of Content

3. Ordering information

The following orderable part numbers are available:

- VHP-DT8M – Supporting the DART-MX8M
- VHP-DT8MM/P – Supporting the DART-MX8MM and DART-MX8MP

4. Heat Sink Kit Content

- 1 x Heat sink.
- 1 x Thermal pad:
  TG-A6200, precut to 20x20, 1.0mm thick. Fits DART-MX8M.
  TG-A6200, precut to 20x20, 1.5mm thick. Fits DART-MX8M-MINI/PLUS.
- 4 x Flat Head Phillips M2x10mm DIN965 SS screws (different screw types may be supplied).

5. Heat Sink Assembly

4.1 Attach the thermal pad on top of the i.MX8M/MINI/PLUS processors located on the DART-MX8M/MINI/PLUS.
Make sure that the two plastic covers, on both sides of thermal pads, are removed before attaching the pad (Please see note under section 4.4 for thermal paste option).

Place for thermal pad on the i.MX8M/MINI/PLUS processors
(Do not stretch the pad)
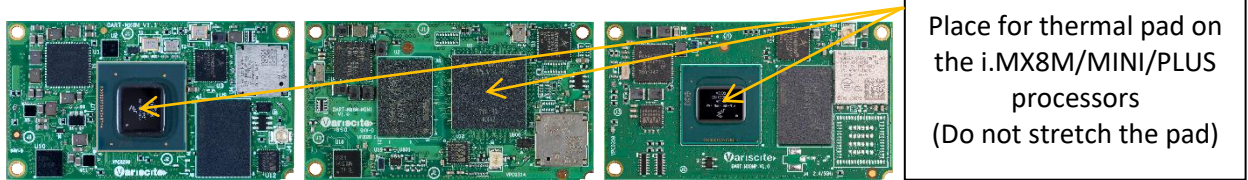
4.2 Assemble the heat sink on top side of the DART-MX8M/MINI/PLUS.
Use the mechanical holes in order to align the heat sink to the DART-MX8M/MINI/PLUS.

Heat Sink alignment holes & screws
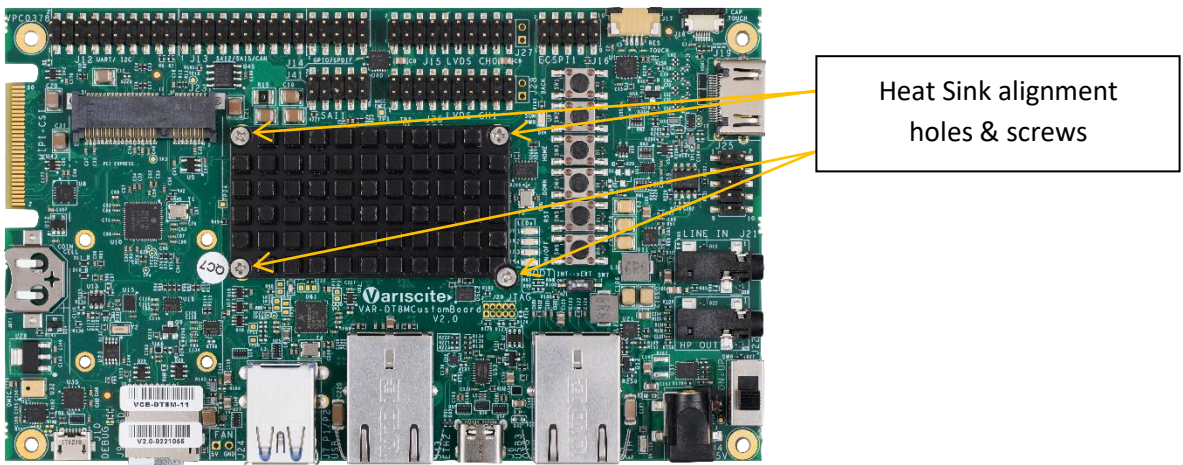
4.3 Insert the M2 screws to the heat sink holes.

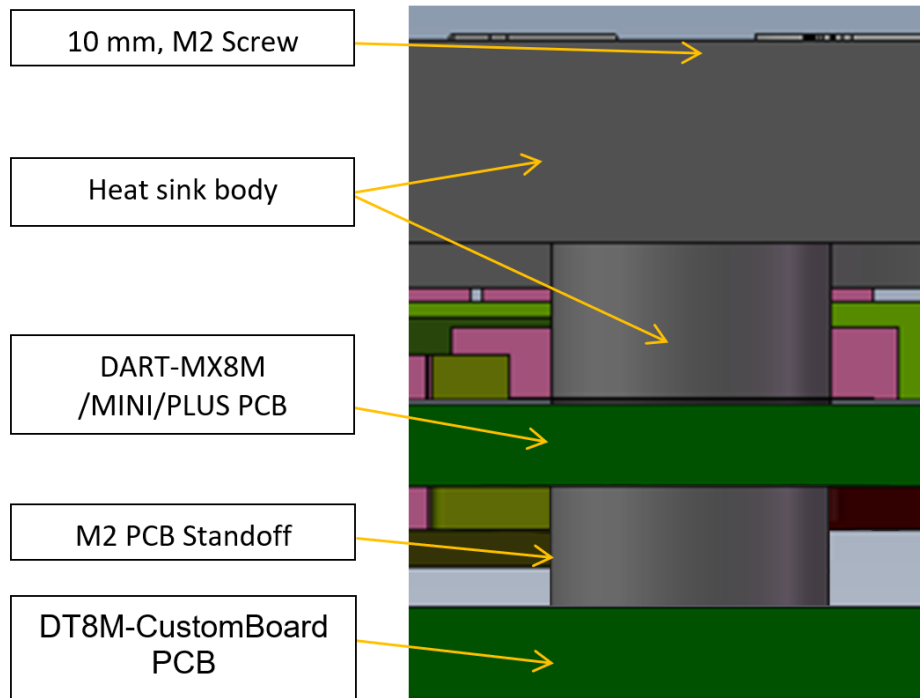4.4 Tight the heat sink to the DART-MX8M/MINI/PLUS using the supplied screws.
Recommended torque for tightening the screws is ~1in-lb (~0.113N-m).

Note:

Due to tolerances of the related components (heat sink, thermal pad, PCB, i.MX8M processor) there might be a small gap between the heat sink and the PCB itself.
It is highly recommended to do the following:

1. Press slightly the heat sink on top of the thermal pad sin order to squeeze the thermal pad on the processor.

2. Tighten the four screws. Pay attention when tightening the last screw that there is no excessive pressure on the PCB which might cause it to deform.

3. If you see excessive pressure is applied, you should not tighten the screw all the way and use Loctite or similar glue to lock the screws.

4. Another alternative is to use thermal paste (grease) instead of thermal pad which bridges the gap between the processor and the heat sink. The thermal paste should have similar thermal conductivity as the thermal pad, 6.0 watt/m-k (by JIS R2618 / ASTM D2326 standard).

Heat Sink assembly sketch

| 10 mm, M2 Screw |
| Heat sink body |
| DART-MX8M /MINI/PLUS PCB |
| M2 PCB Standoff |
| DT8M-CustomBoard PCB |

6. Contact Information

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